CLAIMS

1. An arrangement comprising a circuit board (20) equipped with at least one conductor path (22) and a contact element (44) for contacting an electrical conductor (66) that serves for connection to that circuit board (20), said arrangement comprising the following features:

the circuit board (20) has passthrough orifices (24, 26, 28, 30, 32) in the region of a predetermined conductor path (20);

the contact element (44; 80) has a base part (46; 82) and feet (34, 36, 38, 40, 42; 88, 90, 92, 94) provided thereon for pressing into predetermined orifices (24 to 32) of the circuit board (20);

the contact element (44; 80) is electrically connected in the region of its base part (46; 82) to the predetermined conductor path by means of a soldered connection (74);

the contact element (44; 80) has a contact tongue (54; 96) that is resiliently articulated on the base part (46; 82) and is implemented for contacting the electrical conductor (66).

2. The arrangement according to claim 1, wherein

at least one lateral guidance member (70, 72) for the electrical conductor (66) is provided on the contact element (44).

3. The arrangement according to claim 2, wherein

the lateral guidance member (70, 72) is implemented integrally with the base part (46).

4. The arrangement according to one of the preceding claims, wherein

at least some of the feet (34 to 42) have a reduced width (39) in the region of the free end (38).

5. The arrangement according to one of the preceding claims, wherein

the electrical conductor (66) is inserted between contact tongue (54) and base part (46) and is connected, by means of a welded connection (76, 78), to at least one element of the set to which the base part (46) and the contact tongue (54) belong.

6. The arrangement according to claim 5, wherein

the welded connection (76, 78) is produced by laser welding.

7. The arrangement according to one of the preceding claims, wherein

the electrical conductor (66) is implemented as a flat conductor.

8. The arrangement according to claim 7, wherein

the flat conductor (66) is implemented for mechanical latching with the contact tongue (54; 96).

9. The arrangement according to claim 8, wherein

the contact tongue (54; 96) comprises a projection (97), and the flat conductor (66) is equipped with a recess for engagement of that projection.

10. The arrangement according to one of the preceding claims, wherein

the contact element (44; 80) is equipped with at least one orifice (49) that is implemented, upon preparation for the soldering operation, to receive solder paste in the manner of a reservoir.

11. The arrangement according to claim 10, wherein

the at least one orifice (49) is implemented in a region of the contact element (44; 80) that serves for planar solder joining to the predetermined conductor path (22).

12. The arrangement according to one of the preceding claims, wherein

the connection between the base part and at least one foot comprises

a connecting part (59) that, in a subregion of the spacing between foot (61) and base part (70), exhibits a spacing from the circuit board (20).